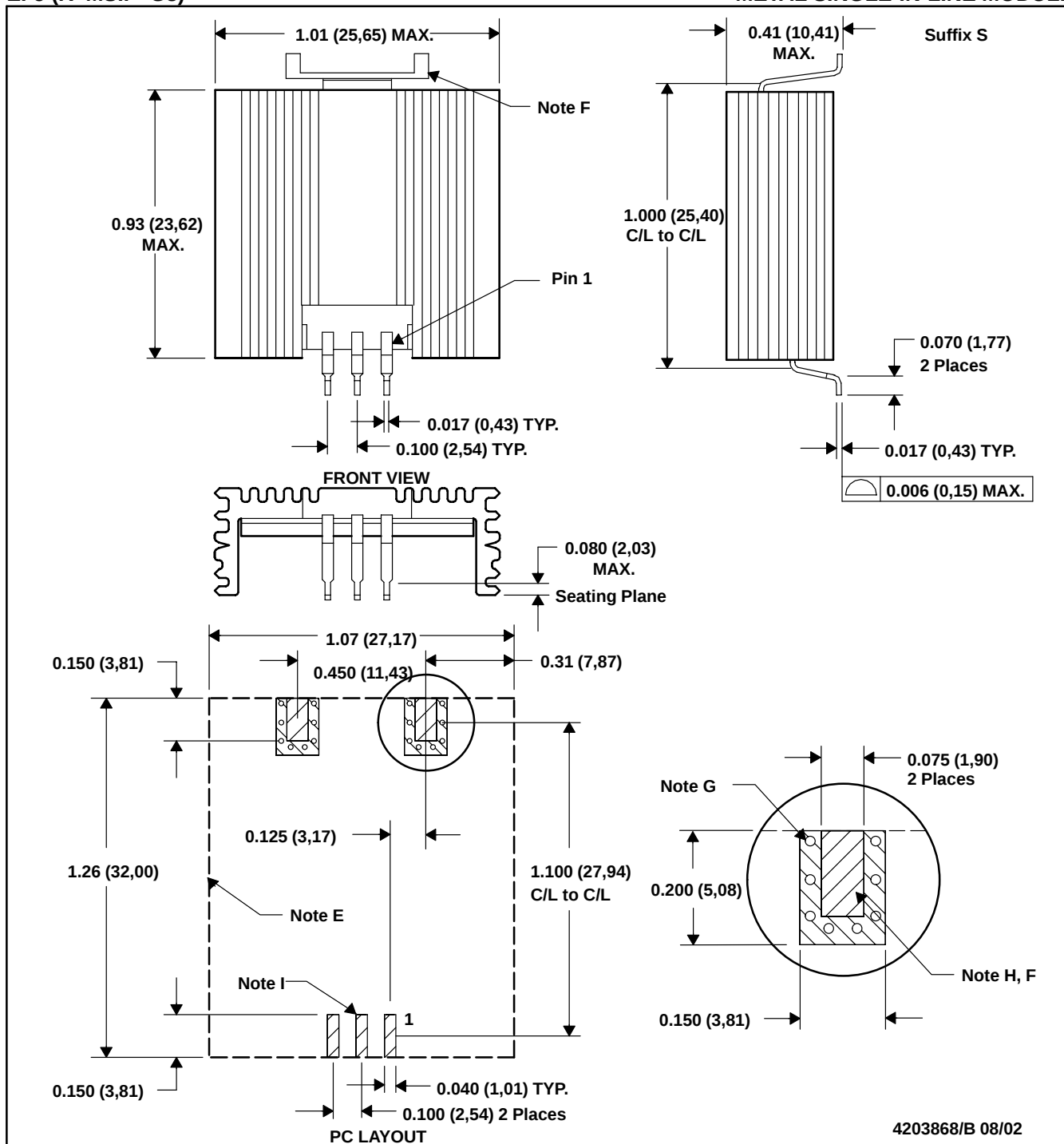


EFJ (R-MSIP-G3)

METAL SINGLE-IN-LINE MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.030 (± 0.76 mm).
 - D. 3 place decimals are ± 0.010 (± 0.25 mm).
 - E. Recommended mechanical keep out area.
 - F. The 2-pin tab is electrically isolated and can be grounded.

- G. Vias are recommended to improve copper adhesion.
- H. Solder mask openings to copper island for solder joints to mechanical pins.
- I. Power pin connections should utilize two or more vias per input, ground and output pin.

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